

AMENDMENTS TO THE SPECIFICATION

IN THE SPECIFICATION:

Please amend the paragraph beginning on page 5, line 11, as follows:

--Please refer to Fig. 4A to Fig. 4B. Fig. 4A to Fig. 4B are schematic diagrams of illustrating how the passive component bridges two leadfingers according to an alternative embodiment. Fig. 4A includes two kinds of leadfingers, which are power leadfingers 92 and ground leadfingers 93. The power leadfingers 92 and ground leadfingers 93 each further includes a first leadfinger section 94 located outside and around the molding compound, and a second leadfinger section 95 located inside of the molding compound. The passive component 96 bridges two adjacent second leadfinger sections 95, and power leadfingers 92 and ground leadfingers 93 connect with the integrated circuit die within the molding compound by metal wires 97. Compared with Fig. 4A, whose power leadfingers 92 and ground leadfingers 93 are adjacent, the embodiment disclosed in Fig. 4B further has signal leadfingers 104 between the power leadfingers 102 and ground leadfingers 103. Consequently, this embodiment includes a busbar 105 for facilitating the passive component 106 to bridge the power leadfingers 102 and the ground leadfingers 103. The busbar 105 in this embodiment is set to extend from the ground leadfinger 103 in

order to make the inner adjacency of the power leadfinger 102. Then
the passive component 106 can bridge the ground leadfinger 103 and
the power leadfinger 102 via the busbar 105 inside the molding
compound of the leadframe package. Therefore, the busbar is
designed to make two leadfingers which are not next to each other
outside the molding compound be adjacent inside the molding
compound. The busbar 105 not only can be set to extends-extend from
the ground any leadfinger 103, but also locates at and located
anywhere so as to bridge for the inner adjacency of two non-
adjacent leadfingers. Still, both power and ground leadfingers 102
and 103 connect to integrated circuit die through metal wires 107.
Fig. 4B is not as same as Fig. 4A, where specifically defines one
leadfinger into the first and second leadfinger section, otherwise,
leadfingers in Fig. 4B are regarded as a part of second leadfinger
sections, resulting in the passive component 106 is within the
molding compound. Additionally, the passive component further
bridges two adjacent first leadfinger sections, locating outside of
the molding compound equivalently.--